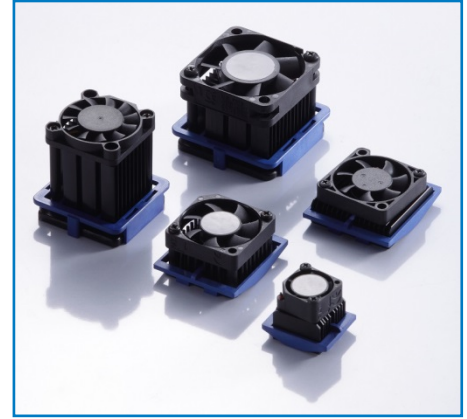


HI-TEMP FAN HEAT SINK – FHP Series

High Operating Temperature Integrated Fan Heat Sinks

DESIGN FEATURES

- Industry-leading maximum operating temperature of 90°C
- Compatible with chipset footprints ranging from 27x27 mm to 40x40 mm
- Common 5VDC @ 0.5 A (max) USB 2.0 fan electrical specifications
- Pin fin heat sink



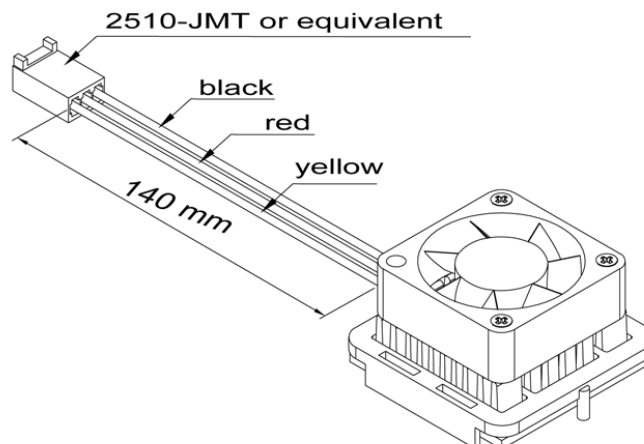
DESCRIPTION

The **FHP** series of integrated-fan heat sinks is uniquely designed to absorb and disperse heat away from high temperature devices while offering key features such as an operating temperature range of -10°C to 90°C, calculated MTTF @ 90°C: 86,858 hours (GEM, 90% confidence) and low profile to fit applications with space constraints. Thermal resistance values range from 3.35°C/W to as low as 1.95°C/W.

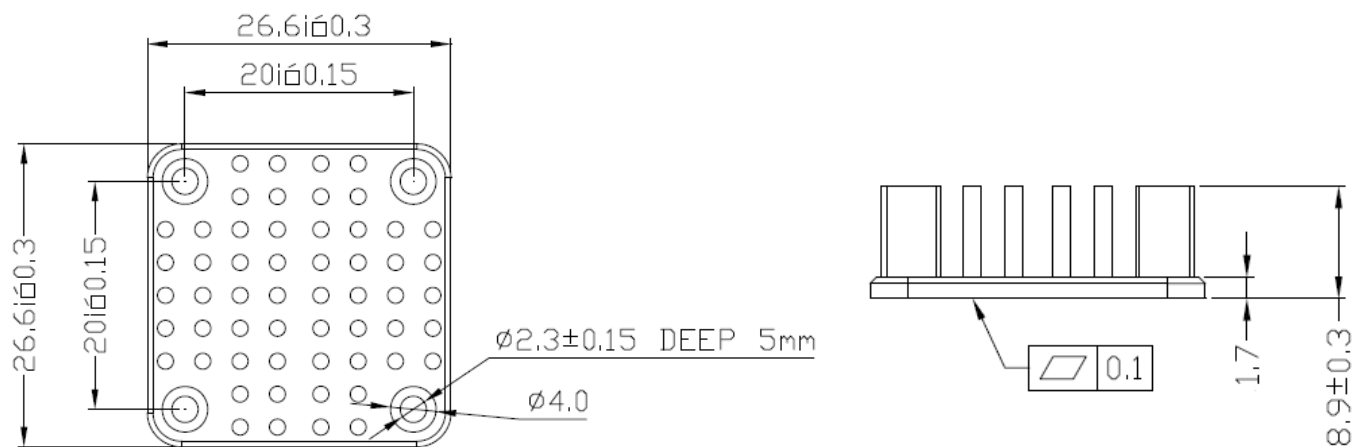
CTS' series of hi-temp fansinks maintain superior thermal dissipation for devices that emit high amount of heat. Our fansinks are available a wide range of footprints and fin heights which make them suitable for many elevated temperature applications such as component testing, burn-in, high density servers, high- speed computing and video, and use in areas where the system airflow is constrained.

Part Number	Length x Width x Height (mm)	Thermal Resistance (R _{TH})
FHP27-27-20	27 x 27 x 20.0 / 34.1 x 29.6 x 20.0 +/- 0.5 mm (with clip)	3.35

PACKAGE



FHP27-27-20



ORDERING INFORMATION

